
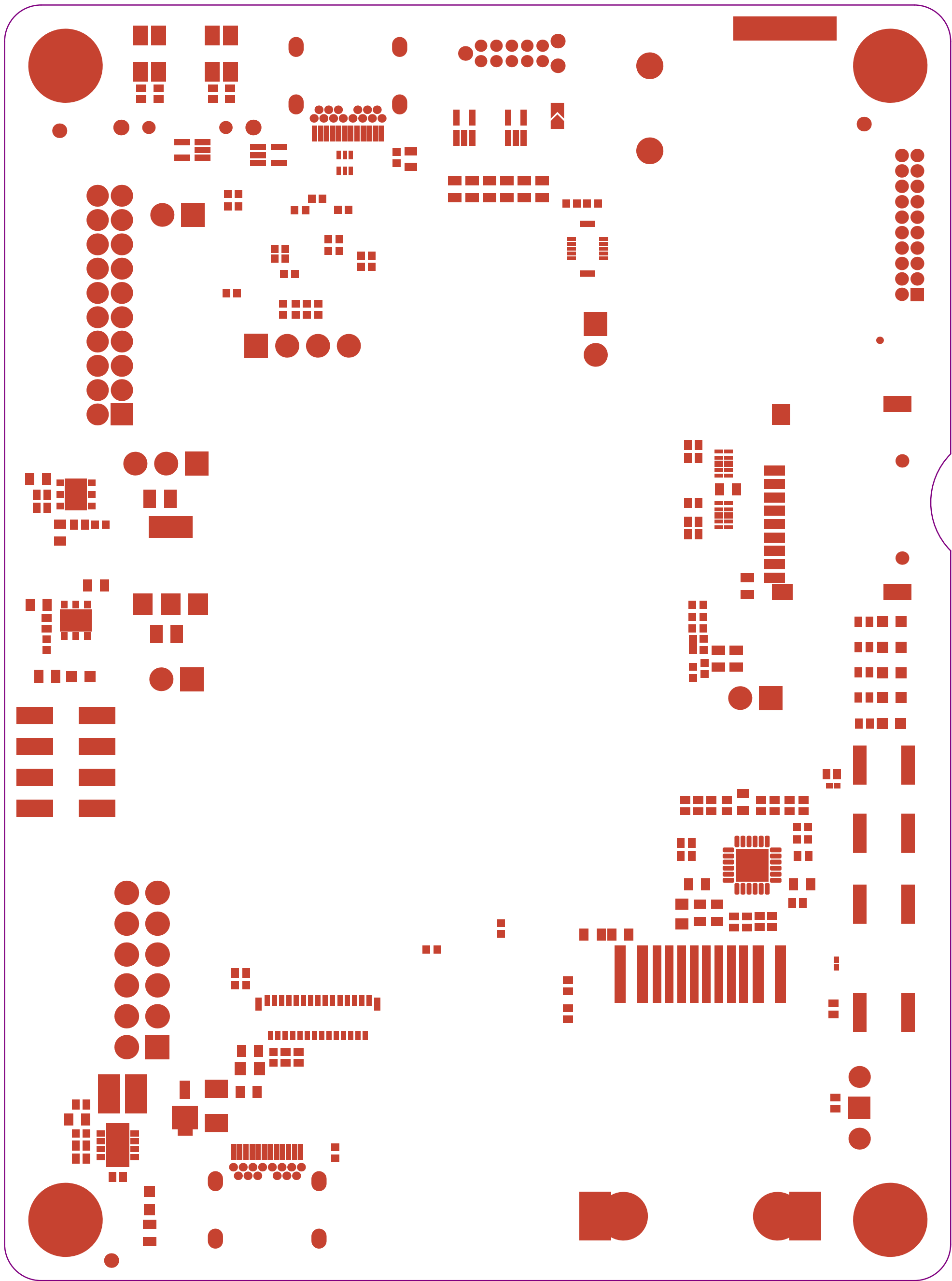

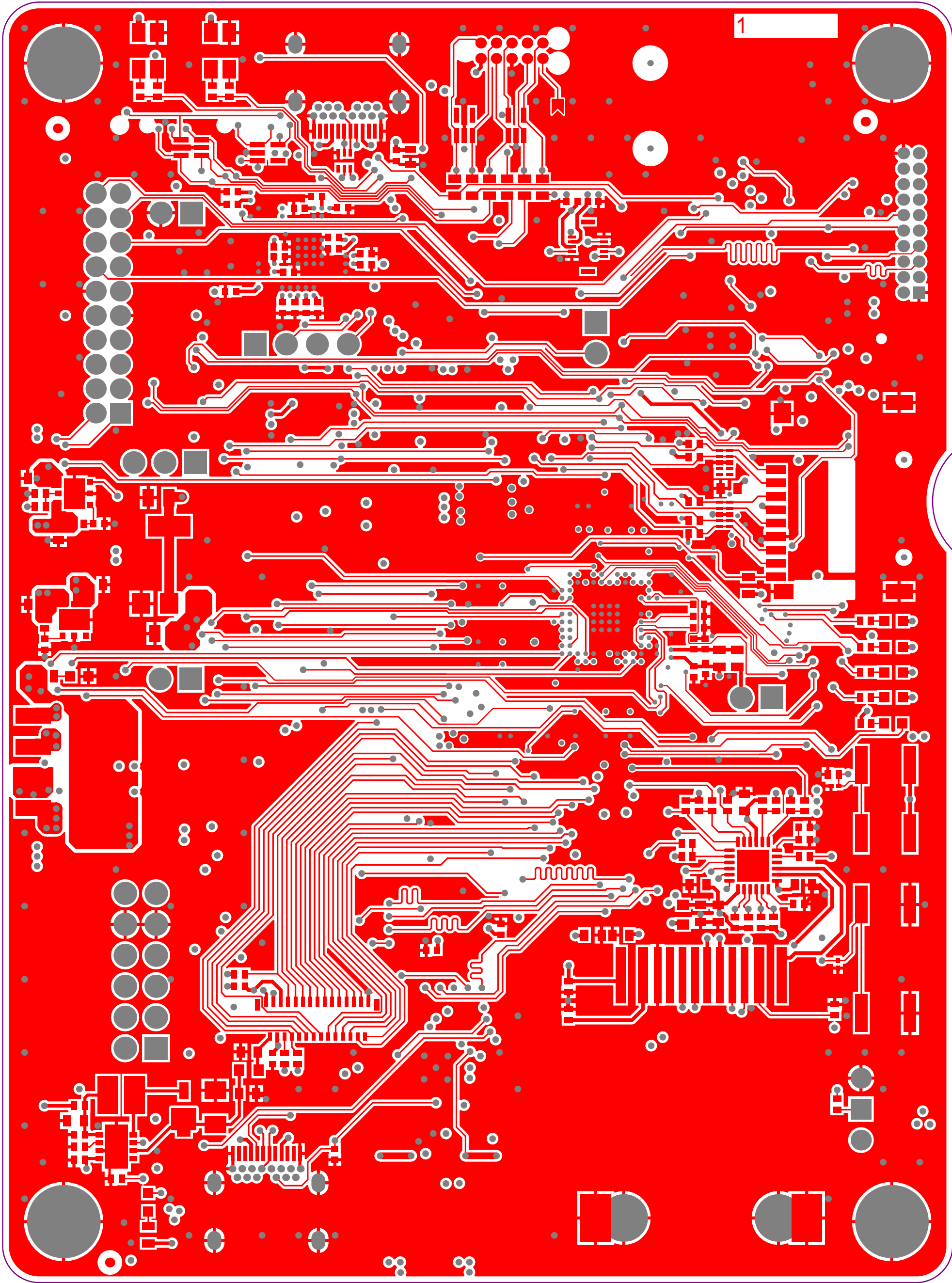



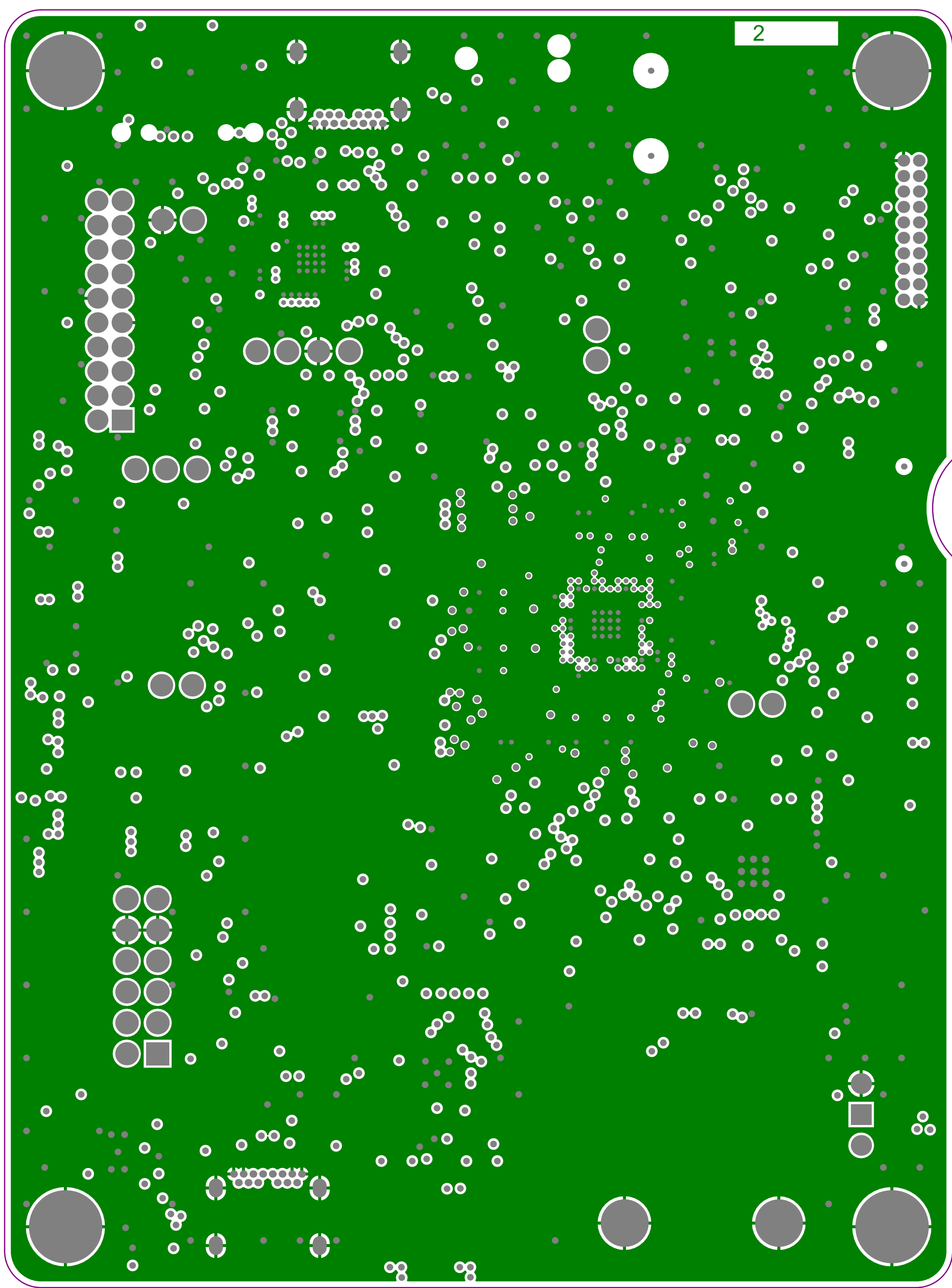
| | | |
|---------------------------|---------------------|--|
| Project: STM32H573I-DK | |  |
| Layer: Top Overlay | Gerber: .GTO | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |




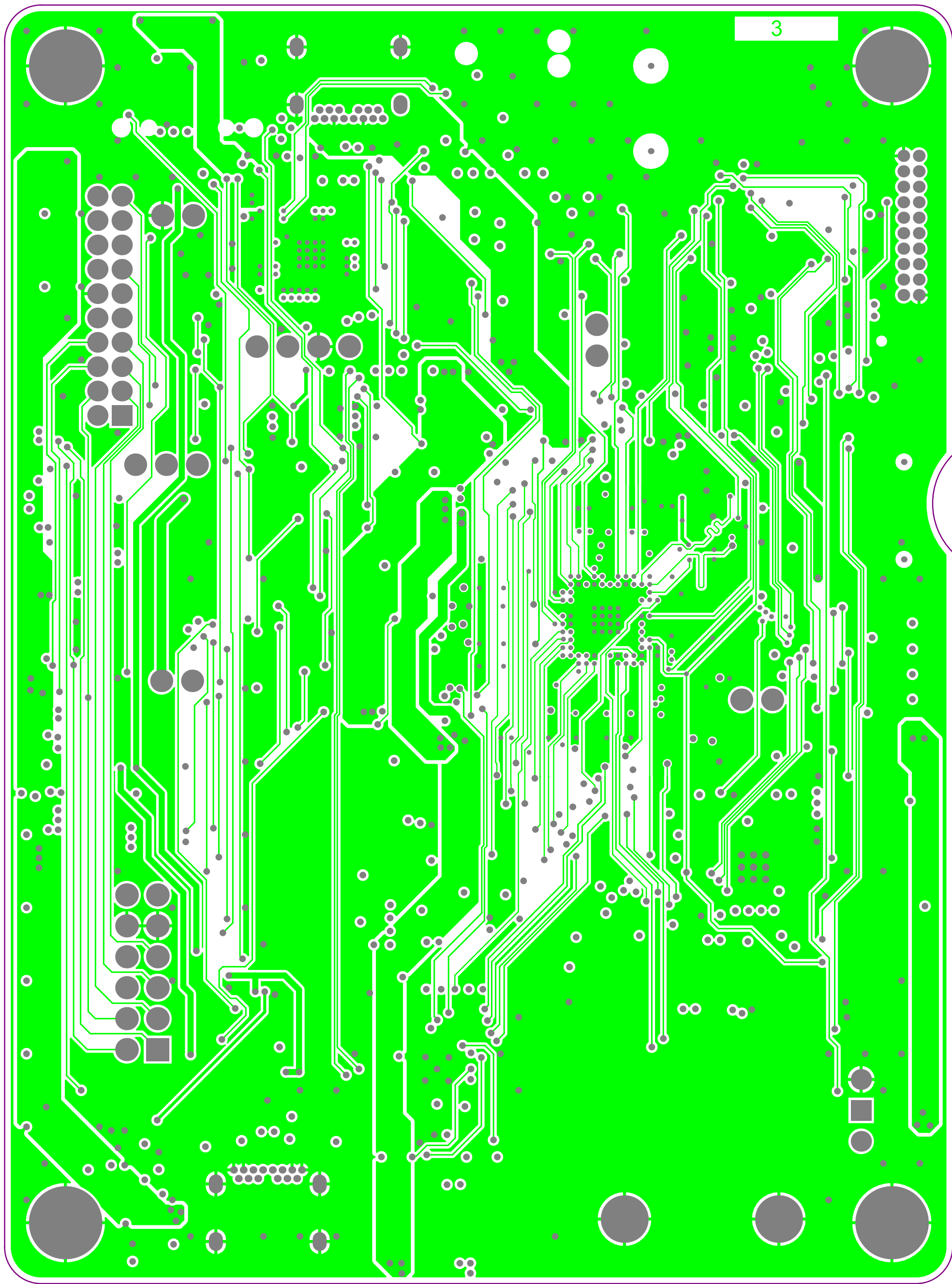
| | | |
|--------------------------|---------------------|--|
| Project: STM32H573I-DK | |  |
| Layer: Top Solder | Gerber: .GTS | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |




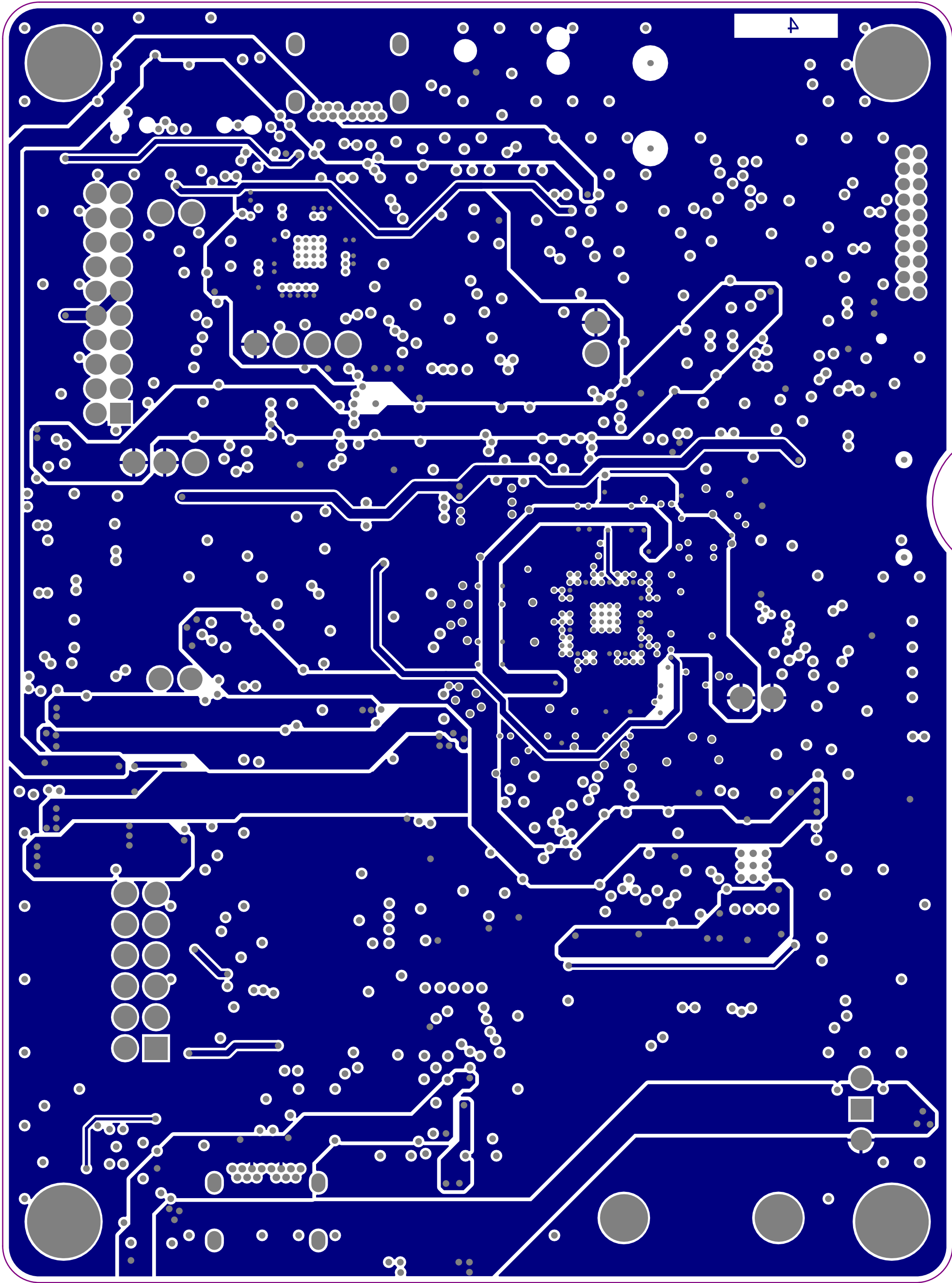
| | | |
|--------------------------|---------------------|--|
| Project: STM32H573I-DK | |  |
| Layer: Top Layer | Gerber: .GTL | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |




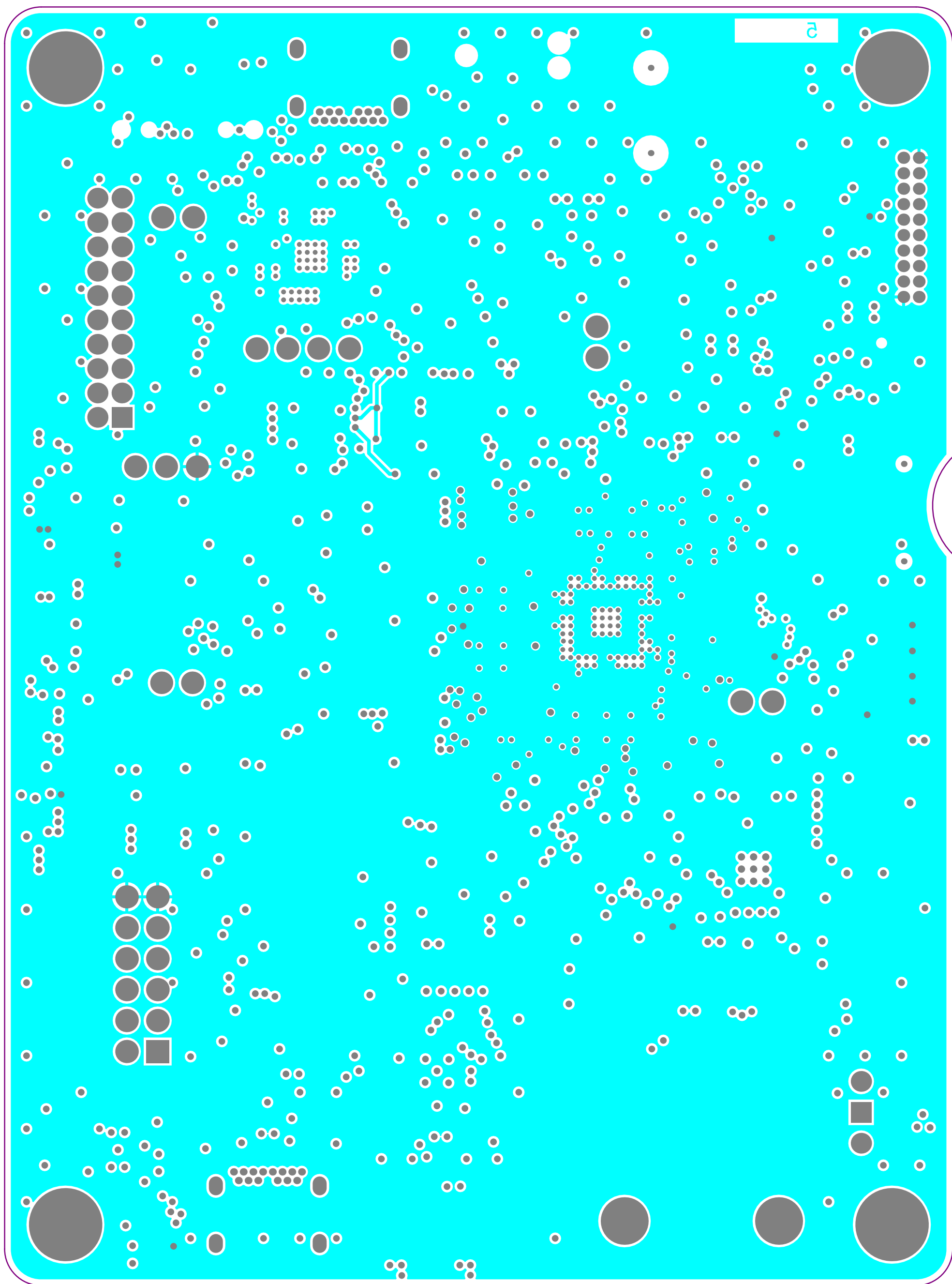
| | | |
|--------------------------|-------------|--|
| Project: STM32H573I-DK | |  |
| Layer: Signal Layer 1 | Gerber: .G1 | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |

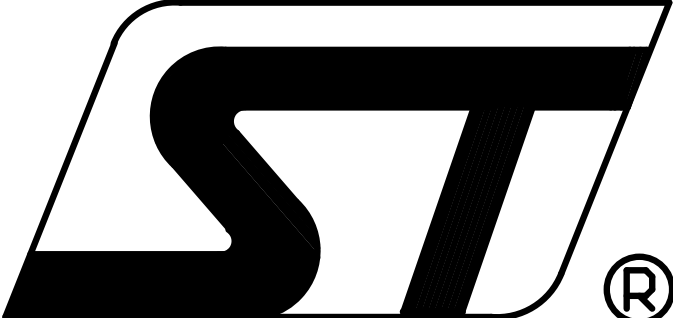


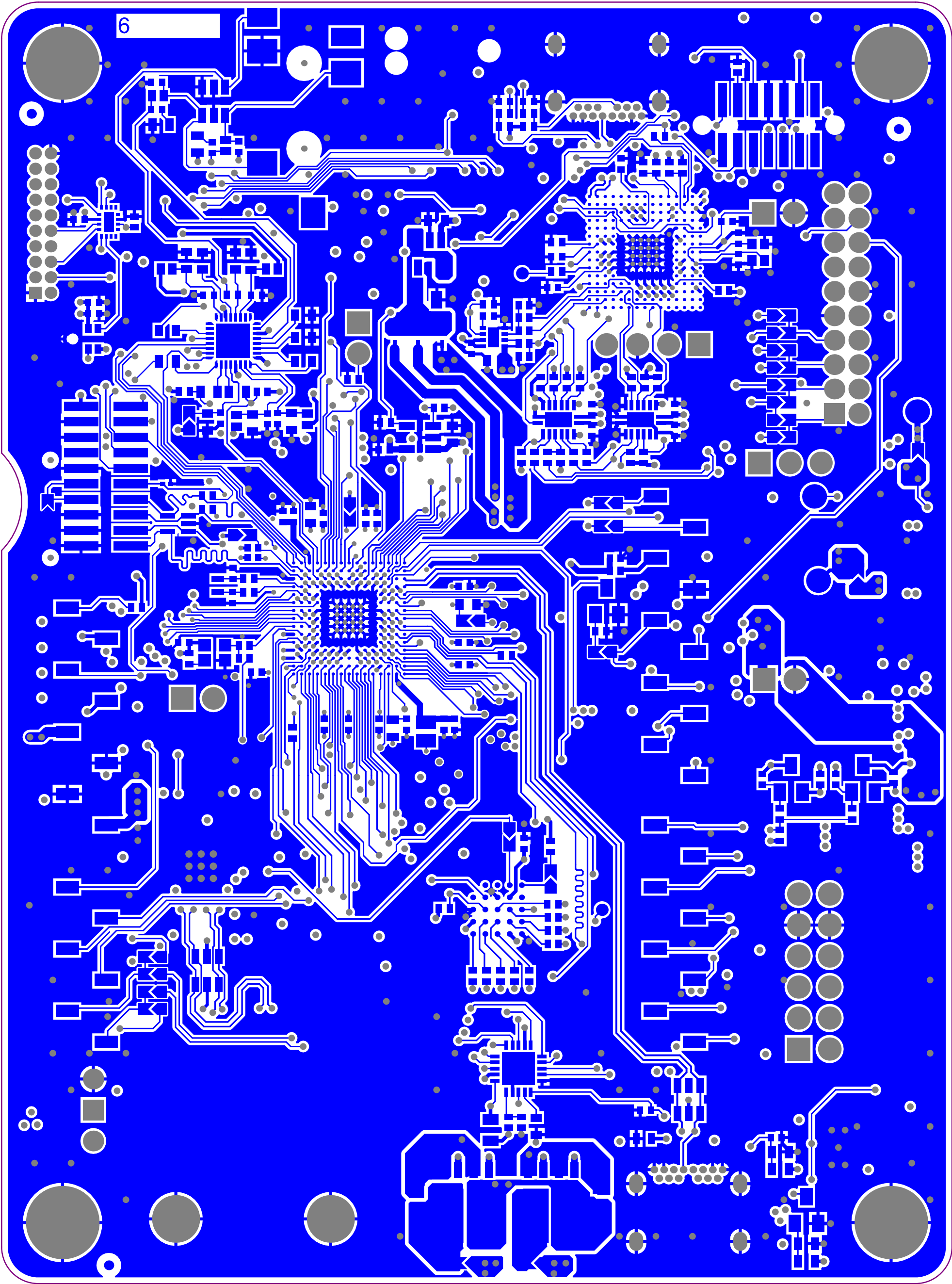
| | | |
|--------------------------|-------------|--|
| Project: STM32H573I-DK | |  |
| Layer: Signal Layer 2 | Gerber: .G2 | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |




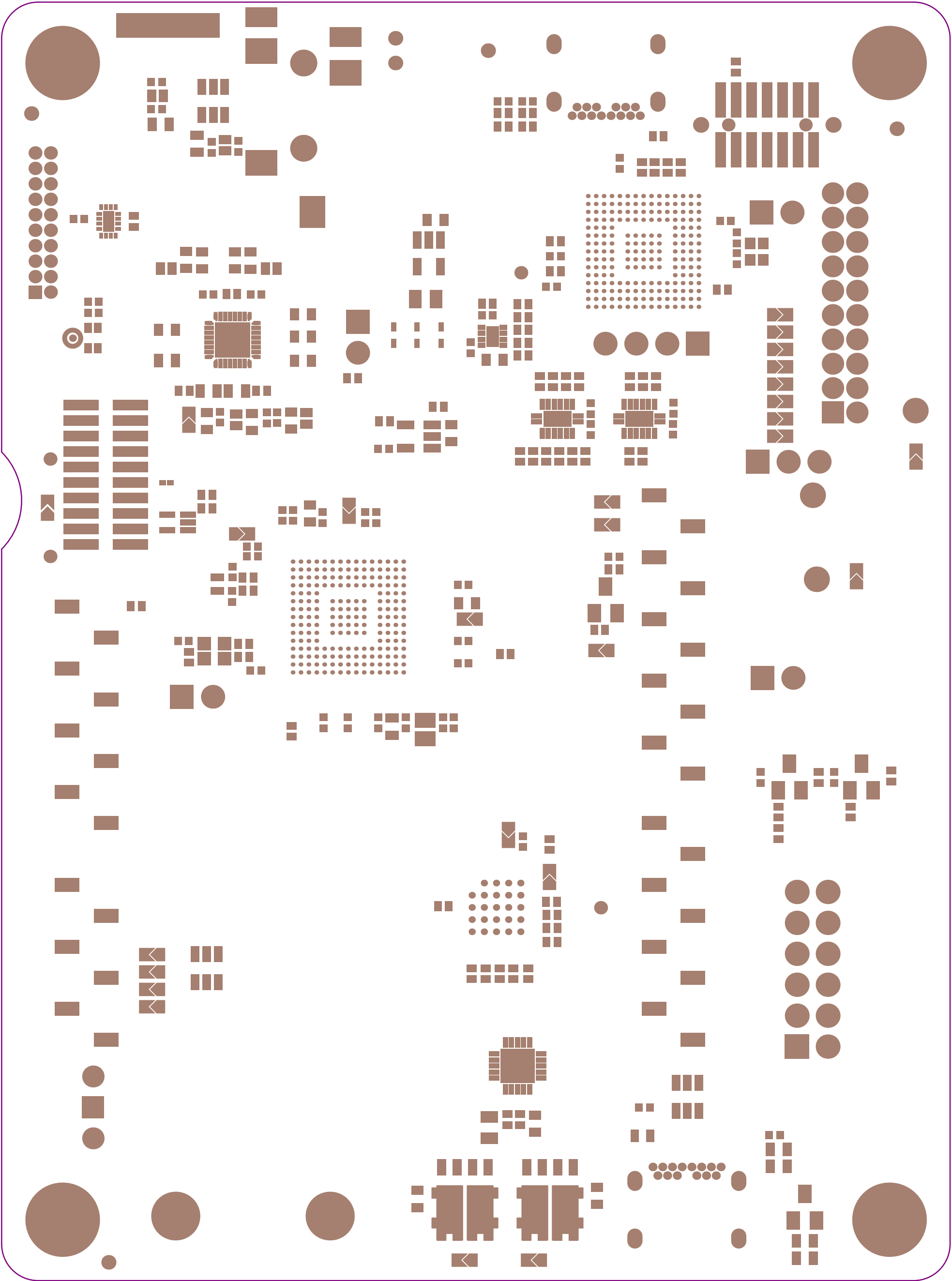
| | | |
|--------------------------|-------------|--|
| Project: STM32H573I-DK | |  |
| Layer: Signal Layer 3 | Gerber: .G3 | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |




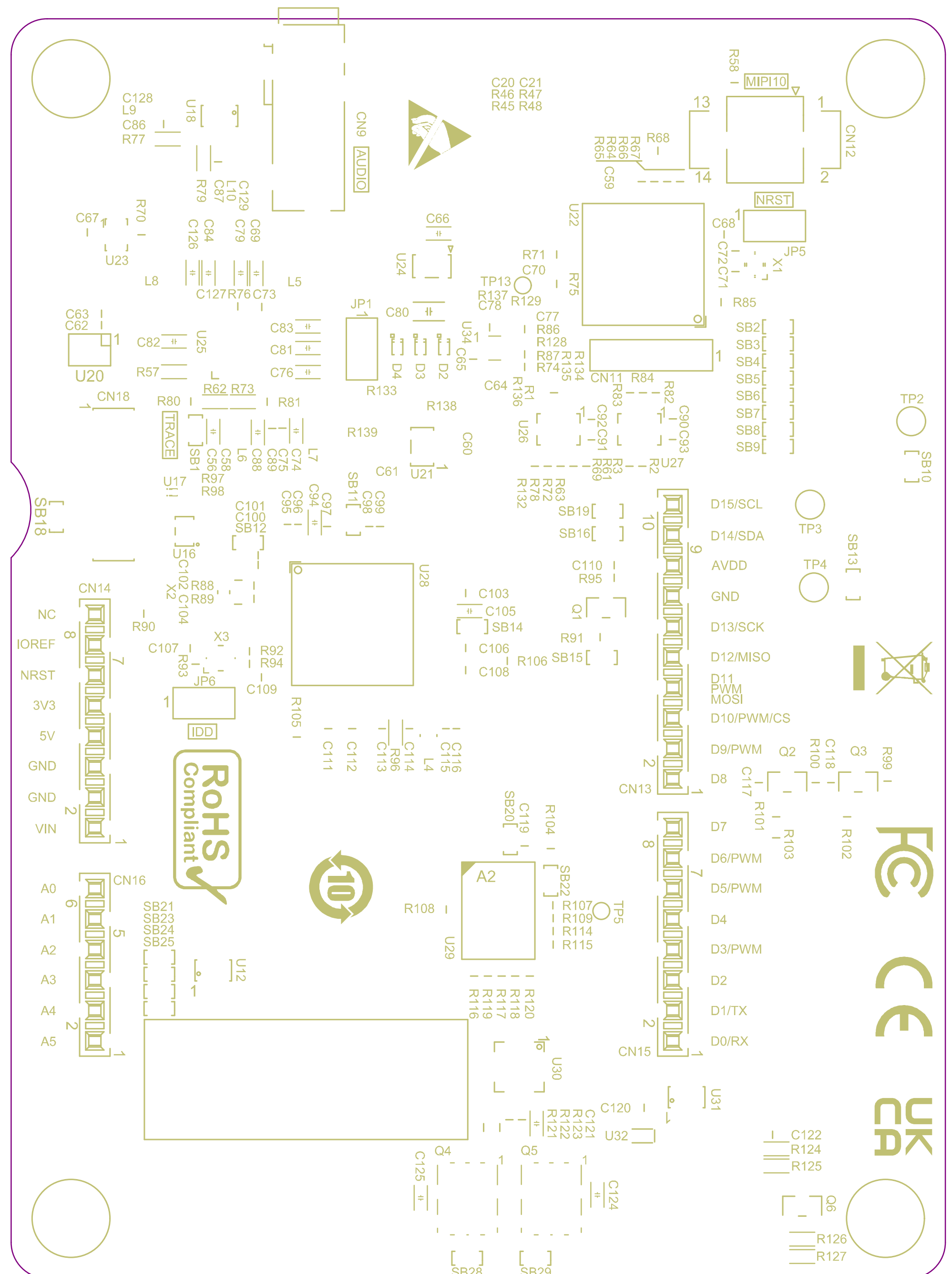
| | | |
|--------------------------|-------------|--|
| Project: STM32H573I-DK | |  |
| Layer: Signal Layer 4 | Gerber: .G4 | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |




| | | |
|--------------------------|-------------|---|
| Project: STM32H573I-DK | |  |
| Layer: Bottom Layer | Gerber:.GBL | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |



| | | |
|--------------------------|--------------|---|
| Project: STM32H573I-DK | |  |
| Layer: Bottom Solder | Gerber: .GBS | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |



| | | |
|--------------------------|-------------|---|
| Project: STM32H573I-DK | |  |
| Layer: Bottom Overlay | Gerber:.GBO | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |

PCB SPECIFICATIONS :

A. MATERIAL :FR-4

☐TG-170

☒TG-150

☐TG-140

B. MATERIAL FAMILY :N/A

C. SOLDERMASK COLOR :

☐GREEN

☐WHITE

☒BLUE

☐BLACK

D. SILKSCREEN COLOR :

☒WHITE

☐YELLOW

☐BLACK

☐Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ENIG

☐IMMERSION SILVER

☐IMMERSION TIN

☐HASL

☐HASL (PB-FREE)

☐GOLDEN FINGER

☐

F. IMPEDANCE CONTROL :

☐NO

☒YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL :

☒SOLDERMASK

☐NON-CONDUCTIVE EPOXY.

☐

H. STACK-UP :SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

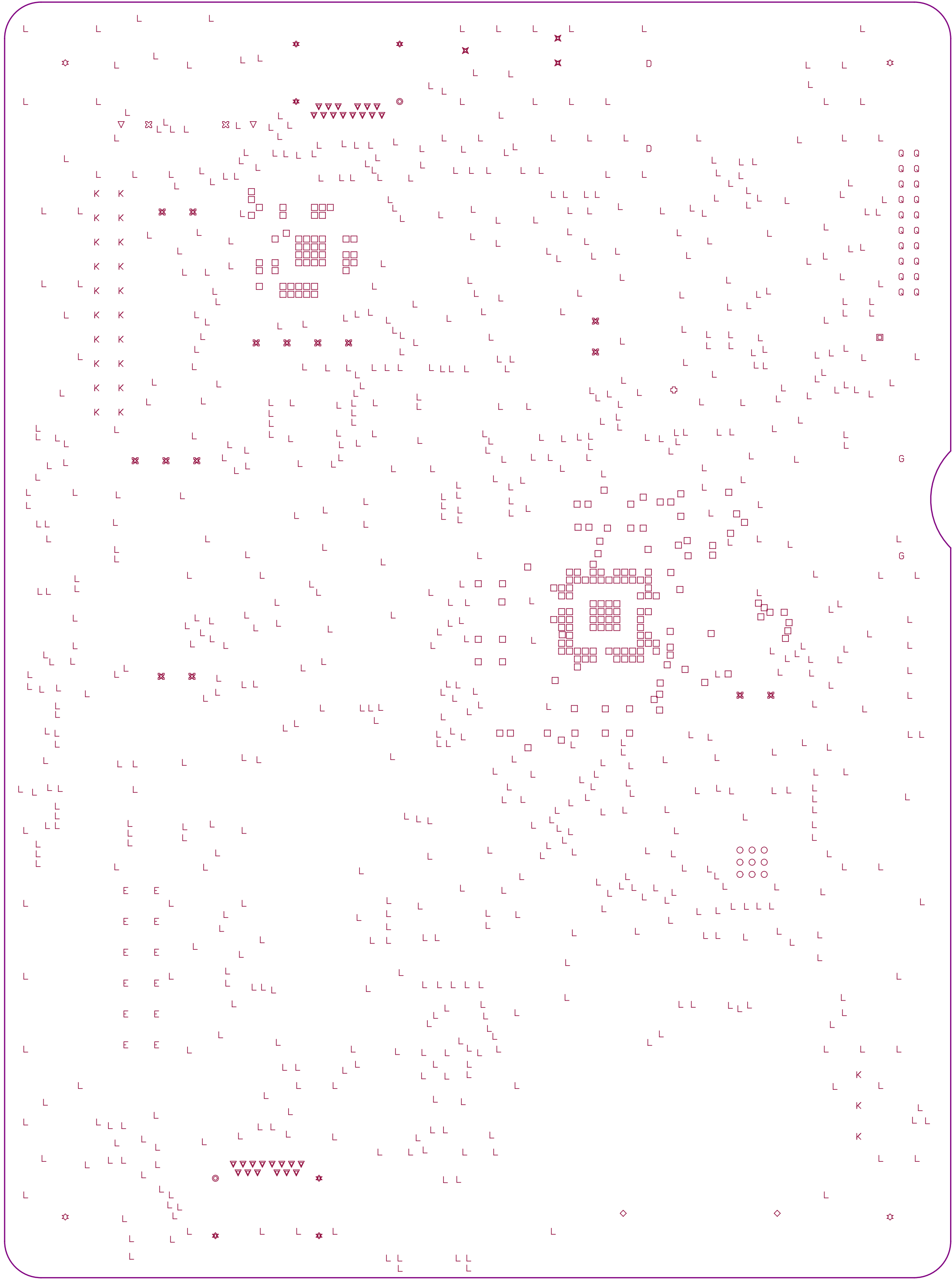
PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6:1 to 8:1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.1mm
GAPS : 0.09mm

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,015mm | 3.5 | |
| 1 | Top Layer | | 0,042mm | | |
| | Dielectric 1 | | 0,100mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Dielectric 2 | | 0,102mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,035mm | | |
| | Dielectric 3 | | 0,946mm | 4.2 | |
| 4 | Signal Layer 3 | | 0,035mm | | |
| | Dielectric 4 | | 0,102mm | 4.2 | |
| 5 | Signal Layer 4 | | 0,035mm | | |
| | Dielectric 5 | | 0,100mm | 4.2 | |
| 6 | Bottom Layer | | 0,042mm | | |
| | Bottom Solder | Solder Resist | 0,015mm | 3.5 | |
| | Bottom Overlay | | | | |



| Symbol | Count | Hole Size | Plated | Hole Type | Drill Layer Pair | Via/Pad |
|--------|------------|---------------------|--------|-----------|--------------------------|---------|
| | 1 | 0,330mm (12,99mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| | 1 | 0,500mm (19,69mil) | NPTH | Round | Top Layer - Bottom Layer | Pad |
| | 2 | 0,450mm (17,72mil) | PTH | Slot | Top Layer - Bottom Layer | Pad |
| | 2 | 0,970mm (38,19mil) | NPTH | Round | Top Layer - Bottom Layer | Pad |
| | 2 | 1,000mm (39,37mil) | NPTH | Round | Top Layer - Bottom Layer | Pad |
| | 2 | 1,190mm (46,85mil) | NPTH | Round | Top Layer - Bottom Layer | Pad |
| | 2 | 2,000mm (78,74mil) | NPTH | Round | Top Layer - Bottom Layer | Pad |
| | 2 | 3,250mm (127,95mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| | 3 | 1,100mm (43,31mil) | NPTH | Round | Top Layer - Bottom Layer | Pad |
| | 4 | 3,500mm (137,79mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| | 6 | 0,450mm (17,72mil) | PTH | Slot | Top Layer - Bottom Layer | Pad |
| | 9 | 0,300mm (11,81mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| | 12 | 1,100mm (43,31mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| | 15 | 1,000mm (39,37mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| | 20 | 0,700mm (27,56mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| | 23 | 0,900mm (35,43mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| | 28 | 0,400mm (15,75mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| | 203 | 0,200mm (7,87mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| | 748 | 0,350mm (13,78mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| | 1085 Total | | | | | |

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

| | | |
|--------------------------|--------------|--|
| Project: STM32H573I-DK | | |
| Layer: Drill Drawing | Gerber: .DRL | |
| Variant: [No Variations] | MB1677 | |
| Date: 29-04-2024 | Rev: D | |